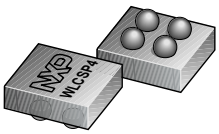


SOT1375-4

WLCSP4, wafer level chip-scale package, 4 terminals, 1.03 mm x 0.94 mm x 0.5 mm body

20 September 2017 Package information

1. Package summary

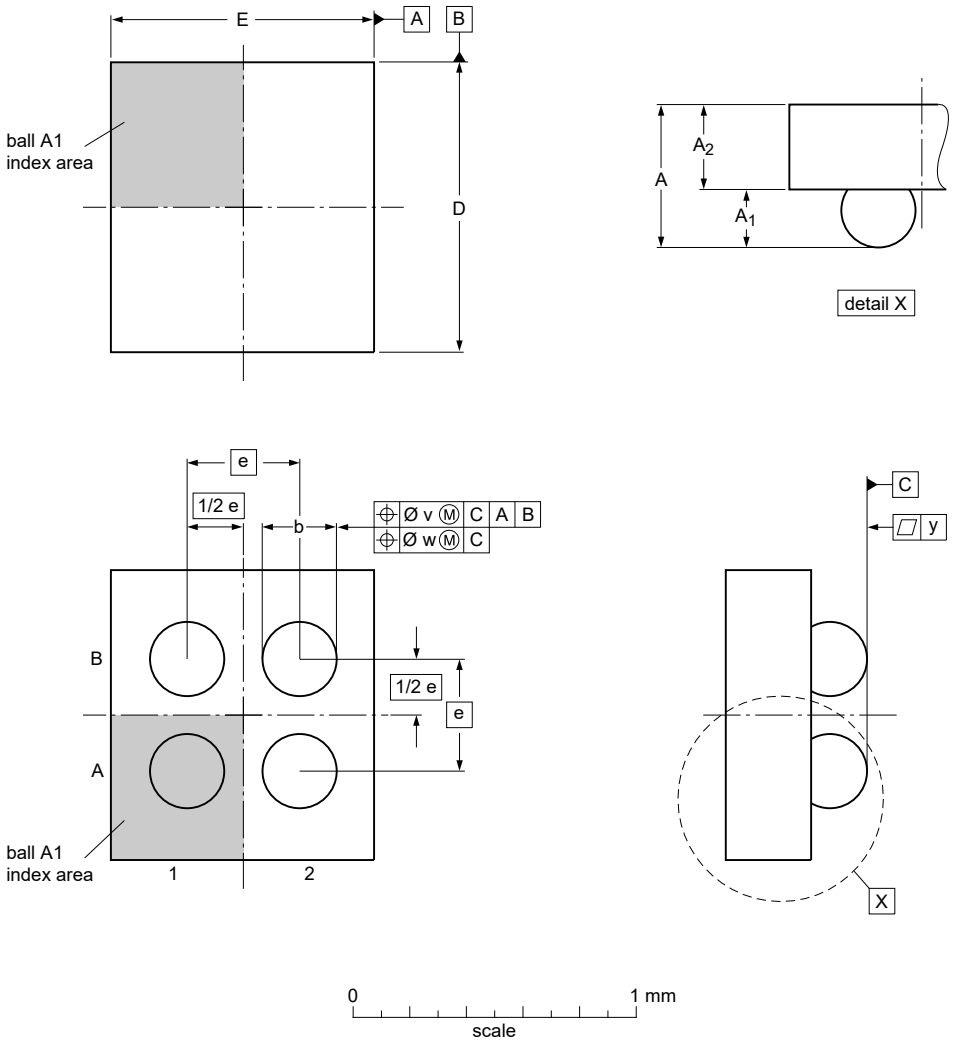
Terminal position code	B (bottom)
Package type descriptive code	WLCSP4
Package type industry code	WLCSP4
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	26-4-2016
Manufacturer package code	SOT1375-4

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1	-	1.03	1.06	mm
E	package width		0.91	-	0.94	0.97	mm
A	seated height		0.46	-	0.5	0.54	mm
A_2	package height		0.275	-	0.3	0.325	mm
e	nominal pitch		-	-	0.4	-	mm
n_2	actual quantity of termination		-	-	4	-	A/A

2. Package outline

WLCSP4: wafer level chip-scale package; 4 bumps; 1.03 x 0.94 x 0.5 mm **SOT1375-4**



Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	b	D	E	e	v	w	y
mm	max	0.54	0.23	0.325	0.29	1.06	0.97				
	nom	0.50	0.20	0.300	0.26	1.03	0.94	0.4	0.05	0.015	0.03
	min	0.46	0.17	0.275	0.23	1.00	0.91				

sot1375-4_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1375-4						~~16-04-06~~ 16-12-05

Fig. 1. Package outline WLCSP4 (SOT1375-4)

3. Soldering

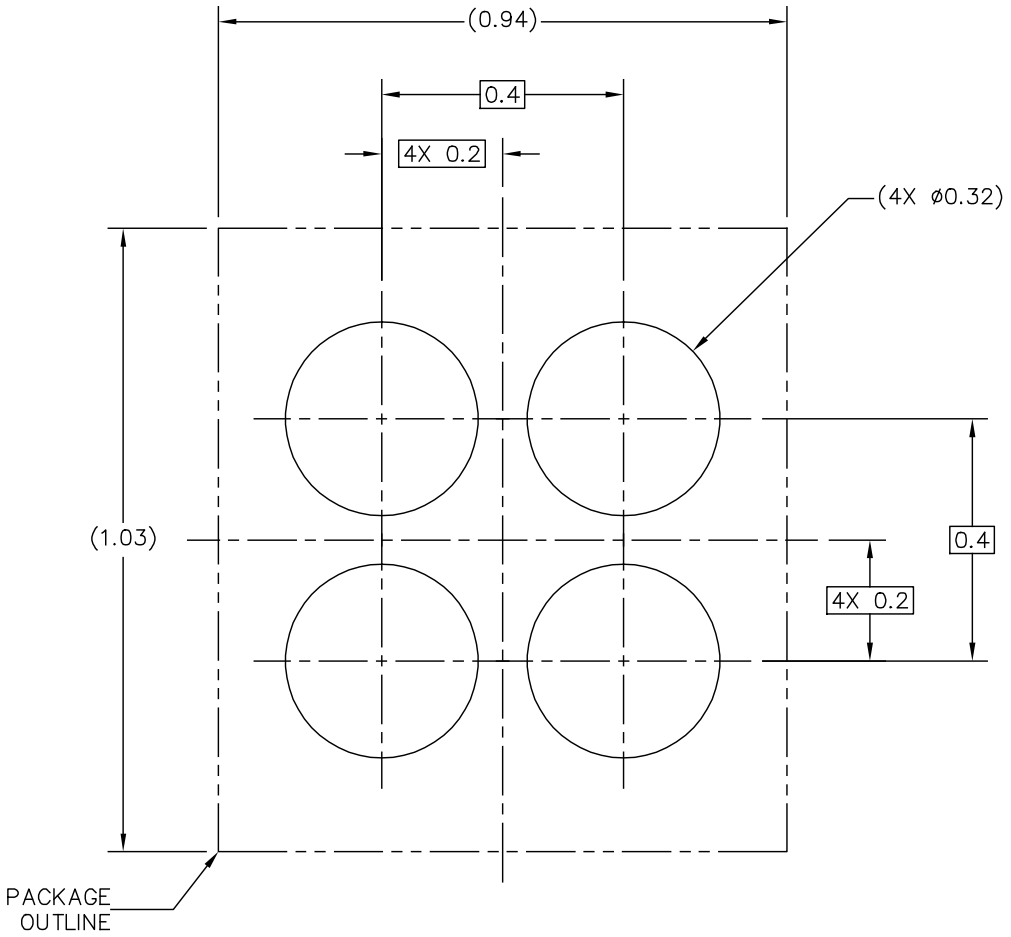


Fig. 2. Reflow soldering footprint for WLCSP4 (SOT1375-4)

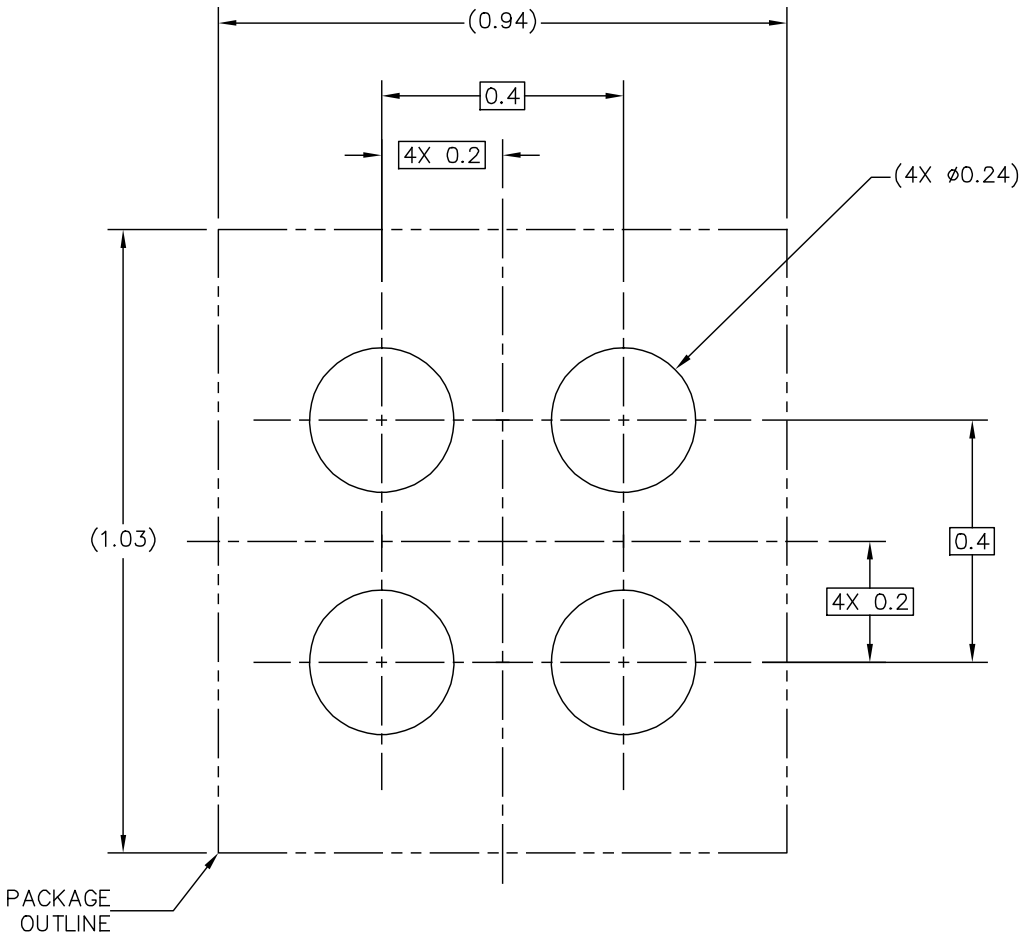


Fig. 3. Reflow soldering footprint part2 for WLCSP4 (SOT1375-4)

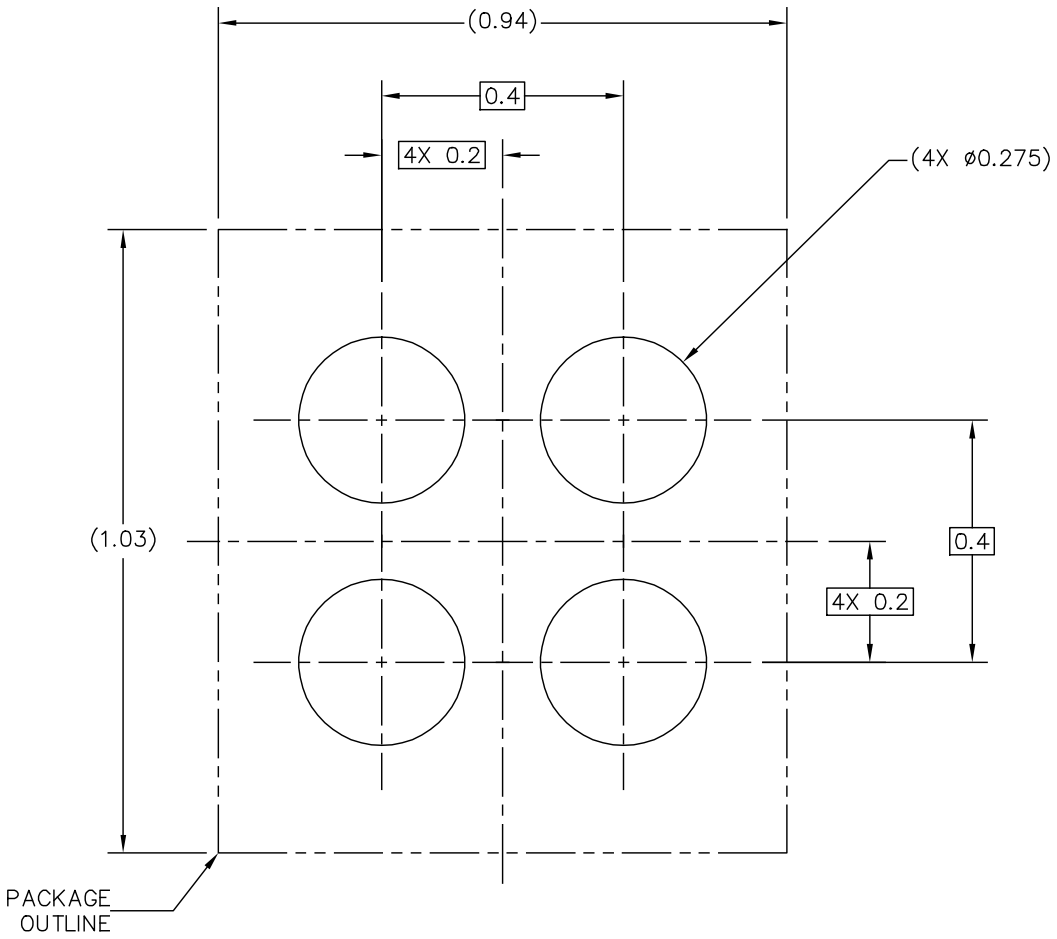


Fig. 4. Reflow soldering footprint part3 for WLCSP4 (SOT1375-4)

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5. Contents

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Date of release: 20 September 2017